

SQA23N50B2

500V 23A N-Channel Enhancement Mode Power MOSFET

Features

- Low on-Resistance: $R_{DS(on)}=0.21\Omega(\text{typ.})$
- Special Process Technology for high ESD Capability
- 100% Avalanche Test
- Good Stability and Uniformity with High E_{AS}

Applications

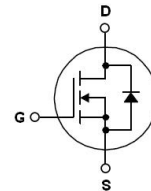
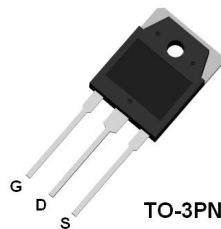
- UPS Applications
- DC-DC Converters and AC-DC Power Supply

Description

The SQA23N50B2 is an N-Channel enhancement mode power MOSFET which using proprietary planar stripe and DMOS technology.

This MOSFET has low static on-resistance and high avalanche energy strength. This device provide excellent switching performance for UPS,DC-DC converters and AC-DC power supply.

Package Type & Internal Circuit



Absolute Maximum Ratings @ $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Ratings	Unit
V _{DSS}	Drain to Source Voltage		500	V
V _{GSS}	Gate to Source Voltage		± 30	V
I _D	Drain Current	T _C =25°C	23	A
		T _C =100°C	14.5	A
I _{DM}	Pulsed Drain Current (Note1)		92	A
P _D	Maximum Power Dissipation	T _C =25°C	280	W
	Derate above 25°C		2.25	W/°C
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		980	mJ
T _J	Operating Junction Temperature Range		-55~+150	°C
T _{STG}	Storage Temperature Range		-55~+150	°C

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{th(J-C)}$	Thermal Resistance, Junction to case	0.45	$^\circ\text{C}/\text{W}$
$R_{th(J-A)}$	Thermal Resistance, Junction to Ambient	50	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** @ $T_c=25\text{ }^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	500	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=11.5A$	-	0.21	-	Ω
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=500V, V_{GS}=0V$	-	-	10	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	-	-	± 100	nA

D-S Diode Characteristics and Maximum Rating @ $T_c=25\text{ }^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Maximum Drain to Source Diode Forward Current		-	-	23	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS}=0V, I_S=23A$	-	0.92	-	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_S=23A,$	-	0.57	-	μs
Q_{rr}	Reverse Recovery Charge	$di/dt=-100A/\mu s$	-	7.85	-	μC

Switching Characteristics @ $T_c=25\text{ }^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$I_D=23A,$ $V_{DD}=250V,$ $R_G=25\Omega$ (Note 3)	-	42	-	ns
t_r	Rising Time		-	79	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	125	-	ns
t_f	Falling Time		-	70	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=25V,$ $f=1.0MHz$	-	3040	-	pF
C_{oss}	Output Capacitance		-	350	-	pF
C_{rss}	Reverse Transfer Capacitance		-	10	-	pF
Q_g	Total Gate Charge	$I_D=23A,$ $V_{DS}=400V$ $V_{GS}=10V$ (Note 3)	-	43	-	nC
Q_{gs}	Gate to Source Charge		-	13	-	nC
Q_{gd}	Gate to Drain Charge		-	14.5	-	nC

Note:

1. Repetitive rating: pulse-width limited by maximum junction temperature
2. $L=5mH, V_{DD}=100V, V_G=10V, @T_c=25^{\circ}C$
3. Essentially independent of operating temperature typical characteristics

Typical Performance Characteristics

Fig. 1. Typical on-Region Characteristics

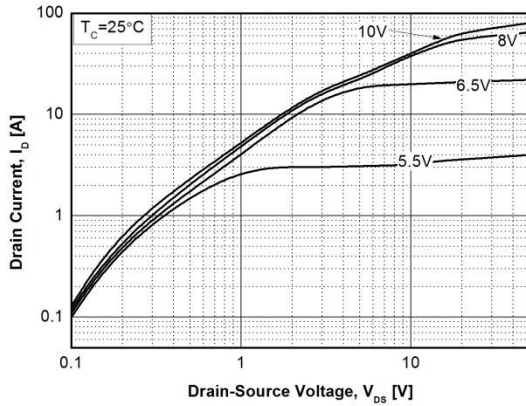


Fig. 2. Typical Transfer Characteristics

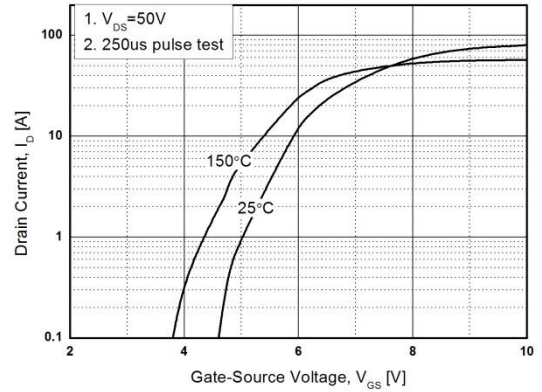


Fig. 3. Static on-Resistance vs. I_D

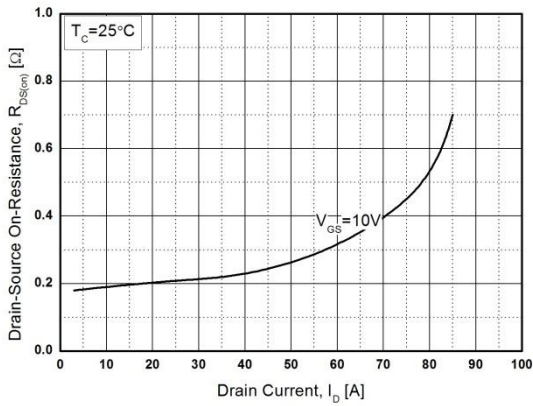


Fig. 4. Body Diode Forward Voltage vs. I_{DR}

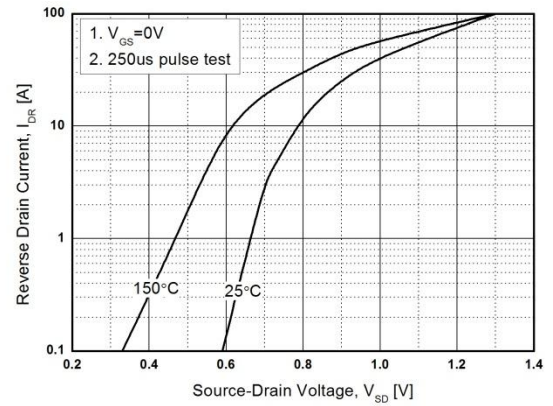


Fig. 5. Capacitance Characteristics

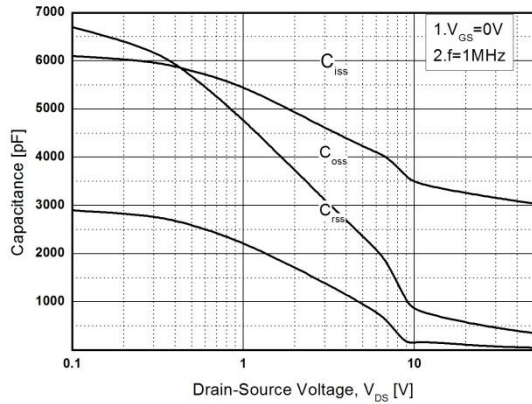
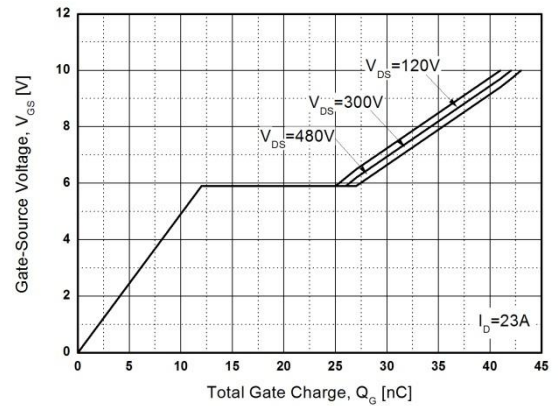


Fig. 6. Gate Charge Characteristics



Typical Performance Characteristics

Fig. 7. Breakdown Voltage vs. Temperature

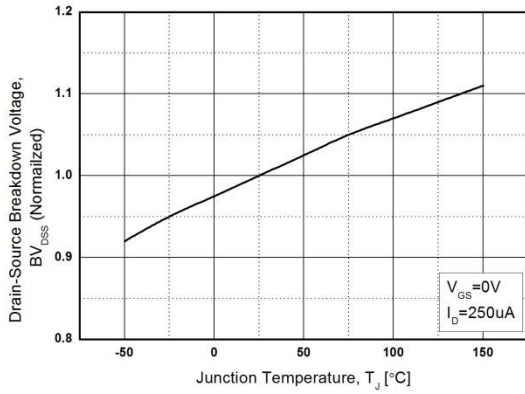


Fig. 8. Static on-Resistance vs. Temperature

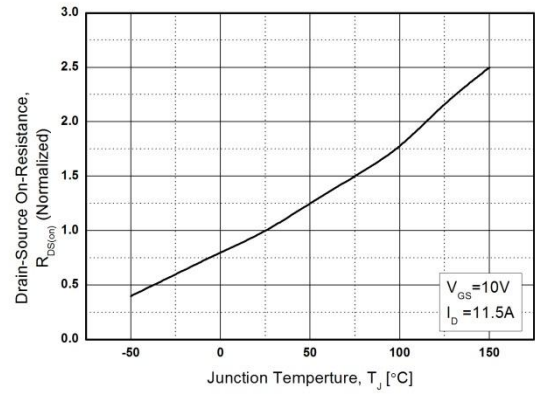


Fig. 9. Maximum Safe Operating Area

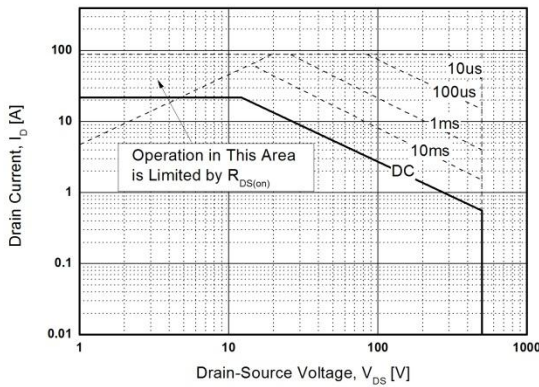


Fig. 10. Maximum Drain Current vs. Temperature

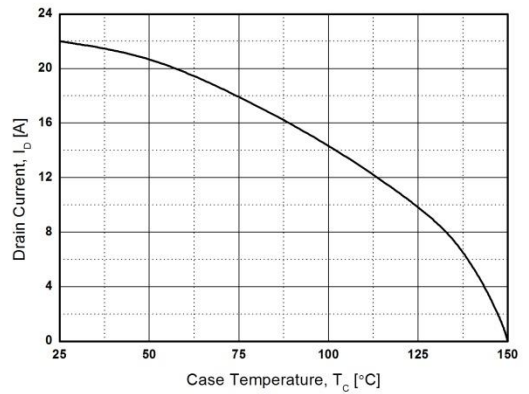
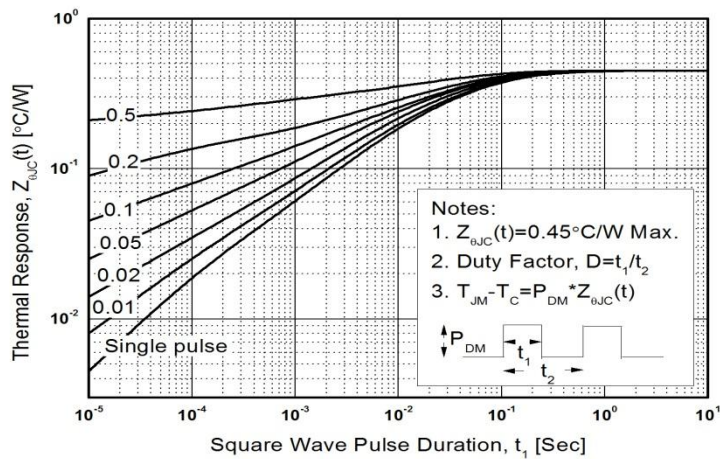


Fig. 11. Transient Thermal Response Curve



Package Dimensions

TO-3PN

(Dimensions in Millimeters)

